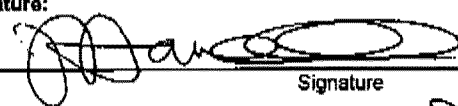


Form PTO-1595 (Rev. 03-11)
OMB No. 0851-0027 (exp. 03/31/2015)

U.S. DEPARTMENT OF COMMERCE
United States Patent and Trademark Office

RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies): Micron Technology, Inc. Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	2. Name and address of receiving party(ies) Name: <u>Round Rock Research, LLC</u> Internal Address: _____ Street Address: _____ P. O. Box 1042 City: <u>Mount Kisco</u> State: <u>New York</u> Country: <u>United States of America</u> Zip: <u>10549</u> Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No
3. Nature of conveyance/Execution Date(s): Execution Date(s): <u>December 30, 2009</u> <input type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Change of Name <input type="checkbox"/> Security Agreement <input type="checkbox"/> Joint Research Agreement <input type="checkbox"/> Government Interest Assignment <input type="checkbox"/> Executive Order 9424, Confirmatory License <input checked="" type="checkbox"/> Other <small>Correction to Reel/Frame 029102/0578 to correct Name of conveying party</small>	4. Application or patent number(s): <input type="checkbox"/> This document is being filed together with a new application. A. Patent Application No.(s) <u>13/568,447</u> B. Patent No.(s) Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No
5. Name and address to whom correspondence concerning document should be mailed: Name: <u>John J. Farrell</u> <u>LERNER, DAVID, LITTENBERG,</u> <u>KRUMHOLZ & MENTLIK, LLP</u> Internal Address: <u>Atty. Dkt.:</u> Street Address: <u>600 South Avenue West</u> City: <u>Westfield</u> State: <u>NJ</u> Zip: <u>07090</u> Phone Number: <u>908-654-5000</u> Fax Number: <u>908-654-7866</u> Email Address: <u>ataylor@ldikm.com</u>	6. Total number of applications and patents involved: 1 7. Total fee (37 CFR 1.21(h) & 3.41) \$ <u>40.00</u> <input checked="" type="checkbox"/> Authorized to be charged to deposit account <input type="checkbox"/> Enclosed <input type="checkbox"/> None required (government interest not affecting title)
8. Payment Information Deposit Account Number <u>12-1095</u> Authorized User Name <u>John J. Farrell</u>	
9. Signature: <div style="display: flex; justify-content: space-between; align-items: flex-end;"> <div style="text-align: center;">  _____ Signature <u>John J. Farrell - 57,291</u> Name of Person Signing </div> <div style="text-align: right;"> <u>November 28, 2012</u> Date </div> </div> <div style="display: flex; justify-content: flex-end; margin-top: 10px;"> Total number of pages including cover sheet, attachments, and documents: 6 </div>	

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RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies):

Joseph M. Jeddalah

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: Round Rock Research, LLC

Internal Address: _____

Street Address: _____

P. O. Box 1042

City: Mount Kisco

State: New York

Country: United States of America Zip: 10549

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): December 30, 2009

☒ Assignment ☐ Merger ☐ Change of Name

☐ Security Agreement ☐ Joint Research Agreement

☐ Government Interest Assignment

☐ Executive Order 9424, Confirmatory License

☐ Other _____

4. Application or patent number(s):

A. Patent Application No.(s)

13/568,447

☐ This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: John J. Farrell
LERNER, DAVID, LITTENBERG,
KRUMHOLZ & MENTLIK, LLP

Internal Address: Atty. Dkt.:

Street Address: 800 South Avenue West

City: Westfield

State: NJ Zip: 07090

Phone Number: 908-654-6000

Fax Number: 908-654-7866

Email Address: ataylor@ldlkm.com

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

☒ Authorized (to be charged to deposit account)

☐ Enclosed

☐ None required (government interest not affecting title)

8. Payment Information

Deposit Account Number 12-1095

Authorized User Name John J. Farrell

9. Signature:



Signature

Date

John J. Farrell - 57,291

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 5

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EXHIBIT A**CONFIRMATORY ASSIGNMENT OF PATENT RIGHTS**

This Confirmatory Assignment of Patent Rights (the "Agreement") is entered into this 30th day of December, 2009 (the "Closing Date"), by and between Micron Technology, Inc., a Delaware corporation ("Assignor"), and Round Rock Research, LLC, a Delaware limited liability company ("Assignee").

WHEREAS, Assignor and Assignee are party to that certain Patent Sale and Transfer Agreement dated on or about the date hereof (as in effect from time to time, the "Patent Sale and Transfer Agreement"); capitalized terms used but not otherwise defined in this Agreement shall have the respective meaning assigned thereto in the Patent Sale and Transfer Agreement;

WHEREAS, pursuant to the Patent Sale and Transfer Agreement, Assignor has agreed to sell, convey, transfer, assign and deliver to Assignee all of Assignor's (and its Subsidiaries') right, title and interest, including Patent Rights, in and to the Patents listed on Schedule A hereto (collectively, the "Assigned Patents");

WHEREAS, Assignee is now desirous of acquiring the entire and exclusive right, title and interest in and to the Assigned Patents in the United States and throughout the world; and

WHEREAS, Assignor is now willing to assign to Assignee all rights, title and interest in and to the Assigned Patents in the United States and throughout the world; and

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor hereby assigns, transfers and conveys to Assignee, its successors, legal representatives and assigns, and Assignee hereby accepts, all of Assignor's right, title and interest in the United States and throughout the world in and to the Assigned Patents and any and all Letters Patent that are or may be granted thereon, and any legal equivalent thereof that may be granted in any country or countries foreign to the United States, in each case including without limitation any extensions, substitutes, continuations, continuations-in-part, divisions, reissues, reexaminations, and renewals thereof, or other equivalents thereof, and further, all rights and privileges pertaining to the Assigned Patents and any and all Letters Patent that are or may be granted thereon, and any legal equivalent thereof that may be granted in any country or countries foreign to the United States, including, without limitation, the right, if any, to petition, sue or otherwise seek and recover damages, profits and any other remedy (monetary, injunctive, declaratory or other) in the United States and anywhere throughout the world for any past, present and future infringement thereof, conversion or misappropriation of, or other injury, offense, violation, breach of duty or wrong relating to, any of the Assigned Patents, or any license, agreement, contract or other matter relating thereto.

Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks of the United States of America and the appropriate officers of all other jurisdictions in which the Assigned Patents are or may be registered or in which applications included among the Assigned Patents are pending, to record the title of Assignee, its successors, legal representatives and assigns, as owner of all right, title and interest in and to the Assigned Patents, and to issue to Assignee, its successors, legal representatives and assigns, all Letters Patent and any legal

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equivalent thereof that may be granted in any country or countries foreign to the United States and recordings of patent rights resulting from any application included among the Assigned Patents, in accordance with the terms of this instrument.

Except to the extent that federal law preempts state law with respect to the matters covered hereby, this Agreement shall be governed by and construed in accordance with the laws of the State of Delaware, without giving effect to any of the principles of conflicts of laws thereof that would result in the application of the laws of another jurisdiction to this Agreement.

This Agreement shall be binding on, and shall inure to the benefit of, the parties hereto and their respective successors and assigns, and may be executed in two or more counterparts, each of which shall be deemed to be an original, but all of which shall constitute one and the same agreement. Each of the parties hereto agrees to accept and be bound by facsimile signatures hereto.

Each party represents that it has taken all necessary action to authorize the execution and delivery of this Agreement.

[The remainder of this page has been intentionally left blank.]

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Dec 30 09 11:27a Henry

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p. 2

IN WITNESS WHEREOF, the parties hereto have caused this Agreement to be executed by their respective duly authorized officers, as of the date first written above.

ASSIGNOR:

MICRON TECHNOLOGY, INC.

By: [Signature]
 Name: Steven R. Appleton
 Title: Chairman and CEO

ASSIGNEE:

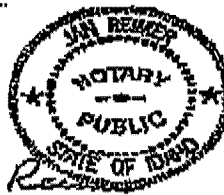
ROUND ROCK RESEARCH, LLC

By: [Signature]
 Name: John Desmarais
 Title: Manager

On this 23rd day of December, 2009, before me appeared Steven R. Appleton, the person who signed this instrument, who acknowledged that he/she signed it as a free act on his/her own behalf or on behalf of the Assignor with authority to do so.

State of IDAHO)

ss.

County of Ada)

[Signature]

[Note that federal patent assignments must also include a cover sheet. See 37 C.F.R. 3.28]

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Schedule A Patents

2003-0103.01/SG	SG	14-Feb-05	METHOD AND APPARATUSES FOR ELECTROCHEMICAL-MECHANICAL POLISHING	Pending		200706011-4
2003-0103.01/US	US	03-Apr-06	METHOD AND APPARATUSES FOR ELECTROCHEMICAL-MECHANICAL POLISHING	Allowed		11/397,419
2003-0154.00/US	US	15-Aug-03	CAM MEMORY ARCHITECTURE AND A METHOD OF FORMING AND OPERATING A DEVICE ACCORDING TO A CAM MEMORY ARCHITECTURE	Issued	14-Jun-05 6906938	10/641,126
2003-0154.01/US	US	14-Jan-05	CAM MEMORY ARCHITECTURE AND A METHOD OF FORMING AND OPERATING A DEVICE ACCORDING TO A CAM MEMORY ARCHITECTURE	Issued	15-Aug-06 7092271	11/034,720
2003-0188.00/US	US	31-Dec-03	APPARATUS AND METHOD FOR MANAGING VOLTAGE BUSES	Issued	22-Aug-06 7096304	10/750,735
2003-0188.01/US	US	27-Jul-06	APPARATUS AND METHOD FOR MANAGING VOLTAGE BUSES	Issued	15-Apr-08 7360006	11/494,034
2003-0192.00/CN	CN	06-Aug-04	MULTIPLE PROCESSOR SYSTEM AND METHOD INCLUDING MULTIPLE MEMORY HUB MODULES	Allowed		200480031785.3
2003-0192.00/DE	DE	15-Mar-06	MULTIPLE PROCESSOR SYSTEM AND METHOD INCLUDING MULTIPLE MEMORY HUB MODULES	Issued	60 2004 017 029.1-08	04780365.5
2003-0192.00/EP	EP	15-Mar-06	MULTIPLE PROCESSOR SYSTEM AND METHOD INCLUDING MULTIPLE MEMORY HUB MODULES	Issued	08-Oct-08 1665056	04780365.5
2003-0192.00/GB	GB	15-Mar-06	MULTIPLE PROCESSOR SYSTEM AND METHOD INCLUDING MULTIPLE MEMORY HUB MODULES	Issued	08-Oct-08 1665056	04780365.5
2003-0192.00/JP	JP	06-Aug-04	MULTIPLE PROCESSOR SYSTEM AND METHOD INCLUDING MULTIPLE MEMORY HUB MODULES	Pending		2008-524680
2003-0192.00/KR	KR	06-Aug-04	MULTIPLE PROCESSOR SYSTEM AND METHOD INCLUDING MULTIPLE MEMORY HUB MODULES	Allowed		10-2006-7004123
2003-0192.00/SG	SG	06-Aug-04	MULTIPLE PROCESSOR SYSTEM AND METHOD INCLUDING MULTIPLE MEMORY HUB MODULES	Issued	31-Jul-07 123002	200601266-0
2003-0192.00/TW	TW	26-Aug-04	MULTIPLE PROCESSOR SYSTEM AND METHOD INCLUDING MULTIPLE MEMORY HUB MODULES	Pending		093125606
2003-0192.00/US	US	28-Aug-03	MULTIPLE PROCESSOR SYSTEM AND METHOD INCLUDING MULTIPLE MEMORY HUB MODULES	Issued	14-Nov-06 7136958	10/653,044
2003-0192.01/US	US	03-Oct-06	MULTIPLE PROCESSOR SYSTEM AND METHOD INCLUDING MULTIPLE MEMORY HUB MODULES	Issued	10-Jun-08 7386649	11/544,352
2003-0192.02/US	US	18-Dec-07	MULTIPLE PROCESSOR SYSTEM AND METHOD INCLUDING MULTIPLE MEMORY HUB MODULES	Issued	25-Aug-09 7581055	12/002,849
2003-0192.03/US	US	20-Jul-09	MULTIPLE PROCESSOR SYSTEM AND METHOD INCLUDING MULTIPLE MEMORY HUB MODULES	Pending		12/505,933
2003-0195.00/US	US	03-Jul-03	A TEMPERATURE SENSING DEVICE IN AN INTEGRATED CIRCUIT	Issued	25-Apr-06 7034507	10/613,236
2003-0195.01/US	US	23-Feb-06	TEMPERATURE SENSING DEVICE IN AN INTEGRATED CIRCUIT	Issued	09-Dec-08 7463542	11/360,164
2003-0195.02/US	US	19-Nov-08	TEMPERATURE SENSING DEVICE IN AN INTEGRATED CIRCUIT	Pending		12/273,626
2003-0231.00/US	US	10-Mar-04	METHOD AND APPARATUS FOR ACHIEVING LOW POWER CONSUMPTION DURING POWER DOWN	Issued	17-Oct-06 7123522	10/797,240
2003-0240.00/US	US	14-Nov-03	REDUCED CELL-TO-CELL SHORTING FOR MEMORY ARRAYS	Issued	15-Aug-06 7091085	10/713,360
2003-0240.01/US	US	26-Jul-05	REDUCED CELL-TO-CELL SHORTING FOR MEMORY ARRAYS	Issued	18-Nov-08 7452770	11/190,736
2003-0240.02/US	US	23-Feb-07	REDUCED CELL-TO-CELL SHORTING FOR MEMORY ARRAYS	Issued	28-Oct-08 7442979	11/678,173
2003-0246.00/US	US	22-Dec-03	METHODS OF FABRICATING LAYERED LENS STRUCTURES	Issued	17-Apr-07 7205526	10/740,597
2003-0246.01/US	US	06-Oct-05	LAYERED LENS STRUCTURES AND DEVICES	Issued	03-Apr-07 7199347	11/244,101
2003-0246.02/US	US	31-Aug-06	LAYERED MICROLENS STRUCTURES AND DEVICES	Pending		11/513,262
2003-0246.03/US	US	20-Dec-06	LAYERED LENS STRUCTURES AND METHODS OF PRODUCTION	Issued	29-Apr-08 7365305	11/641,773